

STF10LN80K5

N-channel 800 V, 0.55 Ω typ., 8 A MDmesh™ K5 Power MOSFET in a TO-220FP package

Datasheet - production data

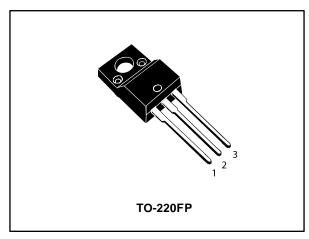
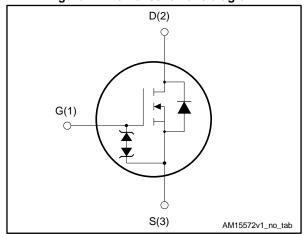


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STF10LN80K5	800 V	0.63 Ω	8 A

- Industry's lowest R_{DS(on)} x area
- Industry's best figure of merit (FoM)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

• Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1: Device summary

Order code	Marking	Package	Packing
STF10LN80K5	10LN80K5	TO-220FP	Tube

Contents STF10LN80K5

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STF10LN80K5 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
$I_D^{(1)}$	Drain current (continuous) at T _C = 25 °C	8	Α
$I_D^{(1)}$	Drain current (continuous) at T _C = 100 °C	5	Α
I _D ⁽²⁾	Drain current pulsed	32	Α
P _{TOT}	Total dissipation at T _C = 25 °C	25	W
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1s; $T_C=25^{\circ}C$)	2500	V
dv/dt (3)	Peak diode recovery voltage slope	4.5	\ //
dv/dt (4)	MOSFET dv/dt ruggedness	50	V/ns
Tj	Operating junction temperature	- 55 to 150	°C
T _{stg}	Storage temperature	- 55 (0 150	

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	R _{thj-case} Thermal resistance junction-case		°C/W
R _{thj-amb}	Thermal resistance junction-ambient	62.5	°C/W

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	I_{AR} Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})		А
E _{AS}	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	240	mJ

⁽¹⁾Limited by maximum junction temperature.

 $^{^{(2)}}$ Pulse width limited by safe operating area

 $^{^{(3)}}I_{SD} \le 8 \text{ A, di/dt} \le 100 \text{ A/}\mu\text{s; } V_{DS} \text{ peak } \le V_{(BR)DSS}$

 $^{^{(4)}}V_{DS} \le 640 \text{ V}$

Electrical characteristics STF10LN80K5

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 5: On/off-state

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ mA}$	800			٧
		$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$			1	μΑ
I _{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$ $T_{C} = 125 ^{\circ}\text{C}$			50	μΑ
I _{GSS}	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			±10	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$	3	4	5	V
R _{DS(on)}	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$		0.55	0.63	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	427	-	pF
Coss	Output capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	43	-	pF
C_{rss}	Reverse transfer capacitance	VG3 - 0 V	-	0.25	-	pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{DS} = 0 to 640 V,	-	72	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related	$V_{GS} = 0 V$		27	-	pF
R_g	Intrinsic gate resistance	$f = 1 \text{ MHz}$, $I_D = 0 \text{ A}$	-	7	-	Ω
Q_g	Total gate charge	$V_{DD} = 640 \text{ V}, I_D = 8 \text{ A}$	-	15	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 10 V	-	4.2	-	nC
Q_{gd}	Gate-drain charge	See Figure 16: "Test circuit for gate charge behavior"	-	9	-	nC

Notes:

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V_{DD} = 400 V, I_{D} = 4 A, R_{G} = 4.7 Ω	ı	11.8	ı	ns
t _r	Rise time	V _{GS} = 10 V See <i>Figure 15: "Test</i>		10	-	ns
t _{d(off)}	Turn-off delay time	circuit for resistive load switching times" and Figure 20: "Switching	-	28	-	ns
t _f	Fall time	time waveform"	1	13	-	ns

 $^{^{(1)}}$ Time related is defined as a constant equivalent capacitance giving the same charging time as Coss when V_{DS} increases from 0 to 80% V_{DSS}

 $^{^{(2)}}$ Energy related is defined as a constant equivalent capacitance giving the same stored energy as Coss when V_{DS} increases from 0 to 80% V_{DSS}

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		8	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		32	Α
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 8 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
t _{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	350		ns
Qrr	Reverse recovery charge	V _{DD} = 60 V, see <i>Figure 17:</i>	-	3.9		μC
I _{RRM}	Reverse recovery current	"Test circuit for inductive load switching and diode recovery times")	-	22.5		Α
t _{rr}	Reverse recovery time	$I_{SD} = 8 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	505		ns
Q _{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 ^{\circ}\text{C}$	-	5		μC
I _{RRM}	Reverse recovery current	see Figure 17: "Test circuit for inductive load switching and diode recovery times"	-	20		Α

Notes:

Table 9: Gate-source Zener diode

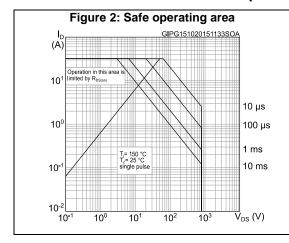
Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit	
V (BR)GSO	Gate-source breakdown voltage	I_{GS} = ± 1mA, I_{D} = 0A	30		-	V	

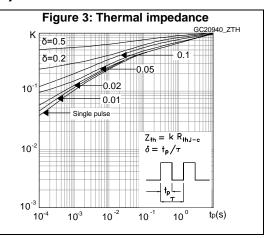
The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

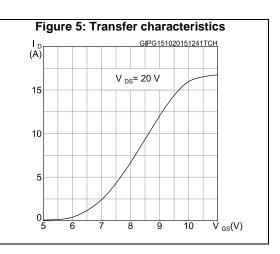
⁽¹⁾Pulse width limited by safe operating area

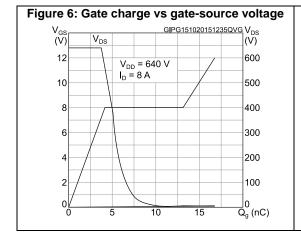
 $^{^{(2)}}$ Pulsed: pulse duration = 300 μ s, duty cycle 1.5%

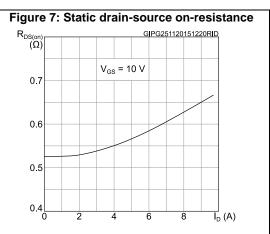
2.2 Electrical characteristics (curves)











STF10LN80K5 Electrical characteristics

Figure 8: Capacitance variations

C (pF)

10³

10²

10¹

10⁻¹

10⁻¹

10⁰

10¹

10¹

10²

V _{DS}(V)

Figure 9: Normalized gate threshold voltage vs temperature

V GS(th) GIPG151020151142VTH (norm.)

1.2

1.0

0.8

0.6

0.4

0.2

-50

0 50

100

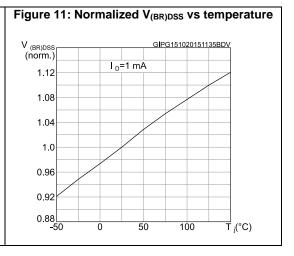
T (°C)

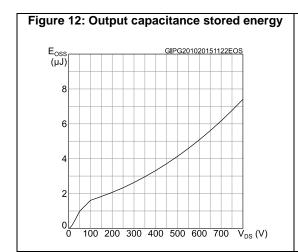
Figure 10: Normalized on-resistance vs temperature

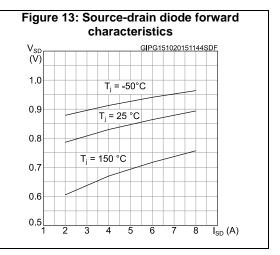
R_{DS(on)} GIPG151020151154RON

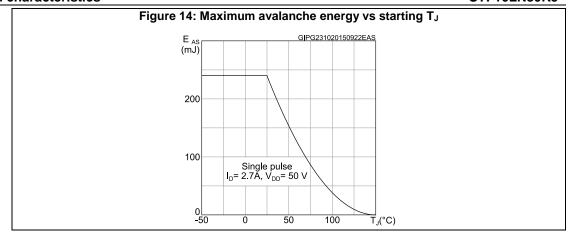
2.6 V_{GS} = 10 V

2.2 1.8 1.4 1.0 0.6 0.2 0.50 100 T_j (°C)









STF10LN80K5 Test circuits

3 Test circuits

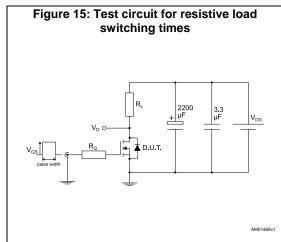


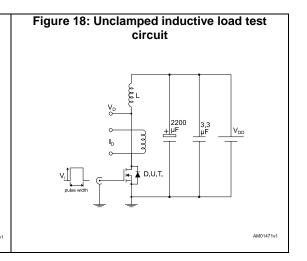
Figure 16: Test circuit for gate charge behavior

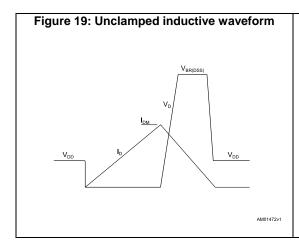
12 V 47 KΩ 100 Ω 1 KΩ

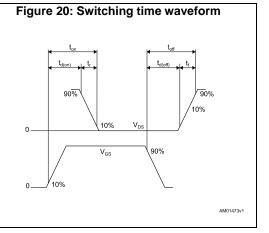
VGS 1 LG= CONST 100 Ω 1 KΩ

VGS 1 LG= CONST 100 Ω 0 VG

AM01469v1







4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

STF10LN80K5 Package information

4.1 TO-220FP package information

Figure 21: TO-220FP package outline

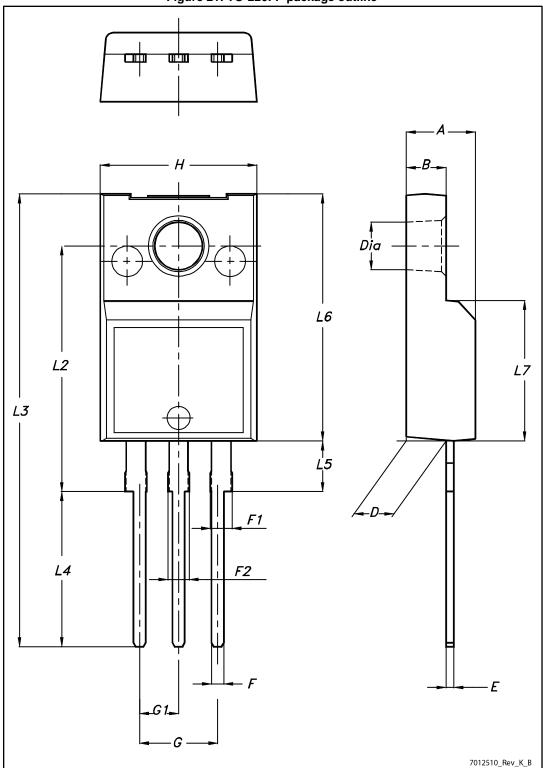


Table 10: TO-220FP package mechanical data

Di	mm		
Dim.	Min.	Тур.	Max.
А	4.4		4.6
В	2.5		2.7
D	2.5		2.75
Е	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
Н	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

STF10LN80K5 Revision history

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
26-May-2015	1	First release.
21-Oct-2015	2	Modified: R _{DS(on)} value in cover page. Modified: Table 2: "Absolute maximum ratings", Table 4: "Avalanche characteristics", Table 5: "On/off-state", Table 6: "Dynamic", Table 7: "Switching times", Table 8: "Source-drain diode". Added: Section 3.1: "Electrical characteristics (curves)". Minor text changes.
01-Dec-2015	3	Modified: Table 2: "Absolute maximum ratings", and Table 3: "Thermal data".

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